# 2.5 V / 3.3 V Any Differential Clock IN to Differential LVPECL OUT ÷1/2/4/8, ÷2/4/8/16 Clock Divider

#### **Features**

The NB6L239 is a high–speed, low skew clock divider with two divider circuits, each having selectable clock divide ratios;  $\div 1/2/4/8$  and  $\div 2/4/8/16$ . Both divider circuits drive a pair of differential LVPECL outputs. (More device information on page 7).

- Maximum Clock Input Frequency, 3.0 GHz
- Input Compatibility with LVDS/LVPECL/CML/HSTL
- Rise/Fall Time 70 ps Typical
- < 10 ps Typical Output-to-Output Skew
- Ex. 622 MHz Input Generates 38.8 MHz to 622 MHz Outputs
- Internal 50 Ω Termination Provided
- Random Clock Jitter < 1 ps RMS
- Divide-by-1 Edge of QA Aligned to QB Divided Output
- Operating Range:  $V_{CC} = 2.375 \text{ V}$  to 3.465 V with  $V_{EE} = 0 \text{ V}$
- Master Reset for Synchronization of Multiple Chips
- V<sub>BBAC</sub> Reference Output
- Synchronous Output Enable/Disable



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#### **MARKING DIAGRAM\***



Bottom View QFN-16

QFN-16 MN SUFFIX CASE 485G



XXXX = Device Code A = Assembly Location

L = Wafer Lot
 Y = Year
 W = Work Week

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.

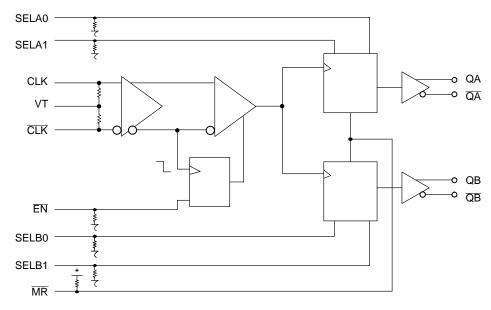


Figure 1. Simplified Logic Diagram

<sup>\*</sup>For additional marking information, refer to Application Note AND8002/D.

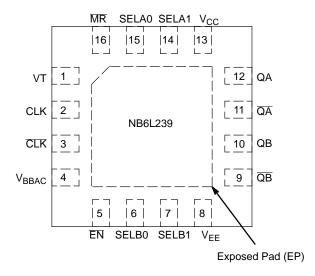


Figure 2. Pinout: QFN-16 (Top View)

**Table 1. PIN DESCRIPTION** 

Pin	Name	I/O	Description
1	VT		Internal 100 $\Omega$ Center–Tapped Termination Pin for CLK and $\overline{\text{CLK}}$ .
2	CLK	LVPECL, CML, LVDS, HSTL Input	Noninverted Differential CLOCK Input.
3	CLK	LVPECL, CML, LVDS, HSTL Input	Inverted Differential CLOCK Input.
4	V <sub>BBAC</sub>		Output Voltage Reference for Capacitor Coupled Inputs, Only.
5	<u>EN</u> *	LVCMOS/LVTTL Input	Synchronous Output Enable
6	SELB0*	LVCMOS/LVTTL Input	Clock Divide Select Pin
7	SELB1*	LVCMOS/LVTTL Input	Clock Divide Select Pin
8	V <sub>EE</sub>	Power Supply	Negative Supply Voltage
9	QB	LVPECL Output	Inverted Differential Output. Typically terminated with 50 $\Omega$ resistor to V <sub>TT</sub> .
10	QB	LVPECL Output	Noninverted Differential Output. Typically terminated with 50 $\Omega$ resistor to V <sub>TT</sub> .
11	QA	LVPECL Output	Inverted Differential Output. Typically terminated with 50 $\Omega$ resistor to V <sub>TT</sub> .
12	QA	LVPECL Output	Noninverted Differential Output. Typically terminated with 50 $\Omega$ resistor to V <sub>TT</sub> .
13	V <sub>CC</sub>	Power Supply	Positive Supply Voltage.
14	SELA1*	LVCMOS/LVTTL Input	Clock Divide Select Pin
15	SELA0*	LVCMOS/LVTTL Input	Clock Divide Select Pin
16	MR**	LVCMOS/LVTTL Input	Master Reset Asynchronous, Default Open High, Asserted LOW
	EP	Power Supply (OPT)	The Exposed Pad on the QFN–16 package bottom is thermally connected to the die for improved heat transfer out of package. The pad is not electrically connected to the die, but is recommended to be electrically and thermally connected to V <sub>EE</sub> on the PC board.

<sup>\*</sup>Pins will default LOW when left OPEN.
\*\*Pins will default HIGH when left OPEN.

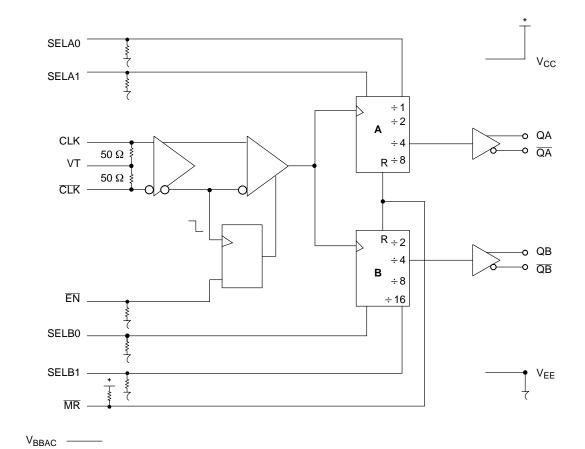


Figure 3. Logic Diagram

**Table 2. FUNCTION TABLES** 

CLK	EN*	MR**	FUNCTION
Х	L H X	H H L	Divide Hold Q Reset Q

Table 3. CLOCK DIVIDE SELECT, QA OUTPUTS

SELA1*	SELA0*		QA Outputs
L L H	<b>⊣ π ⊣ π</b>	Divide by Divide by Divide by Divide by	/ 2 / 4

Table 4. CLOCK DIVIDE SELECT, QB OUTPUTS

SELB1*	SELB0*	QB Outputs
LLHH	<b>⊣ π ⊣ π</b>	Divide by 2 Divide by 4 Divide by 8 Divide by 16

<sup>¬ =</sup> High–to–Low Transition

X = Don't Care

<sup>\*</sup>Pins will default LOW when left OPEN.

<sup>\*\*</sup>Pins will default HIGH when left OPEN.

**Table 5. ATTRIBUTES** 

Characte	ristics	Value
Internal Input Pulldown Resistor Internal Input Pullup Resistor	75 kΩ 75 kΩ	
ESD Protection	> 1500 V > 150 V > 1000 V	
Moisture Sensitivity, Indefinite Ti	me Out of Drypack (Note 1)	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count		367
Meets or exceeds JEDEC Spec	EIA/JESD78 IC Latchup Test	

<sup>1.</sup> For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

# **MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V <sub>CC</sub>	Positive Mode Power Supply	V <sub>EE</sub> = 0 V		3.6	V
VI	Input Voltage	V <sub>EE</sub> = 0 V	$V_{EE} \le V_{I} \le V_{CC}$	3.6	V
l <sub>out</sub>	Output Current	Continuous Surge		50 100	mA mA
I <sub>BB</sub>	V <sub>BBAC</sub> Sink/Source			± 0.5	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm		41.6 35.2	°C/W °C/W
$\theta_{\text{JC}}$	Thermal Resistance (Junction-to-Case)	Standard Board		4.0	°C/W
T <sub>sol</sub>	Wave Solder	< 3 sec @ 248°C		265	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

## Table 6. DC CHARACTERISTICS, CLOCK INPUTS, LVPECL OUTPUTS

 $(V_{CC} = 2.375 \text{ V to } 3.465 \text{ V}, V_{EE} = 0 \text{ V})$ 

			−40°C			25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
I <sub>EE</sub>	Power Supply Cur- rent	30	40	50	30	40	50	30	40	50	mA	
V <sub>OH</sub>	Output HIGH Voltage (Notes 2, 3)  V <sub>CC</sub> = 3.3 V  V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> -1150 2150 1350	V <sub>CC</sub> -1060 2240 1440	V <sub>CC</sub> -950 2350 1550	V <sub>CC</sub> -1100 2200 1400	V <sub>CC</sub> -1015 2285 1485	V <sub>CC</sub> - 900 2400 1600	V <sub>CC</sub> -1050 2250 1450	V <sub>CC</sub> -980 2320 1520	V <sub>CC</sub> - 850 2450 1650	mV	
V <sub>OL</sub>	Output LOW Voltage (Notes 2, 3)  V <sub>CC</sub> = 3.3 V  V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> -1870 1430 630	V <sub>CC</sub> -1760 1540 740	V <sub>CC</sub> -1630 1670 870	V <sub>CC</sub> -1820 1480 680	V <sub>CC</sub> -1700 1600 800	V <sub>CC</sub> -1580 1720 920	V <sub>CC</sub> -1770 1530 730	V <sub>CC</sub> -1660 1640 840	V <sub>CC</sub> -1530 1770 970	mV	

#### **DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED** (Figures 7, 10)

V <sub>th</sub>	Input Threshold Reference Voltage (Note 4)	100		V <sub>CC</sub> – 100	100		V <sub>CC</sub> – 100	100		V <sub>CC</sub> – 100	mV
V <sub>IH</sub>	Single-ended Input HIGH Voltage	V <sub>th</sub> + 100		V <sub>CC</sub>	V <sub>th</sub> + 100		V <sub>CC</sub>	V <sub>th</sub> + 100		V <sub>CC</sub>	mV
V <sub>IL</sub>	Single-ended Input LOW Voltage	V <sub>EE</sub>		V <sub>th</sub> – 100	V <sub>EE</sub>		V <sub>th</sub> – 100	V <sub>EE</sub>		V <sub>th</sub> – 100	mV
V <sub>BBAC</sub>	Output Voltage Reference @ 100 $\mu$ A (Note 7) $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	V <sub>CC</sub> -1460 1840 1040	V <sub>CC</sub> -1330 1970 1170	V <sub>CC</sub> -1200 2100 1300	V <sub>CC</sub> -1460 1840 1040	V <sub>CC</sub> -1340 1960 1160	V <sub>CC</sub> -1200 2100 1300	V <sub>CC</sub> -1460 1840 1040	V <sub>CC</sub> -1350 1950 1150	V <sub>CC</sub> -1200 2100 1300	mV

#### DIFFERENTIAL INPUT DRIVEN DIFFERENTIALLY (Figures 8, 9, 11) (Note 6)

$V_{IHD}$	Differential Input HIGH Voltage	100		V <sub>CC</sub>	100		V <sub>CC</sub>	100		V <sub>CC</sub>	mV
V <sub>ILD</sub>	Differential Input LOW Voltage	V <sub>EE</sub>		V <sub>CC</sub> – 100	V <sub>EE</sub>		V <sub>CC</sub> – 100	V <sub>EE</sub>		V <sub>CC</sub> – 100	mV
V <sub>CMR</sub>	Input Common Mode Range (Differ- ential Cross-point Voltage) (Note 5)	50		V <sub>CC</sub> – 50	50		V <sub>CC</sub> – 50	50		V <sub>CC</sub> – 50	mV
V <sub>ID</sub>	Differential Input Voltage (V <sub>IHD(CLK)</sub> – V <sub>ILD(CLK)</sub> ) and (V <sub>IHD(CLK)</sub> –V <sub>ILD(CLK)</sub> )	100		V <sub>CC</sub> – V <sub>EE</sub>	100		V <sub>CC</sub> – V <sub>EE</sub>	100		V <sub>CC</sub> – V <sub>EE</sub>	mV
R <sub>TIN</sub>	Internal Input Ter- mination Resistor	45	50	55	45	50	55	45	50	55	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Input and output parameters vary 1:1 with  $V_{CC}$ . 3. Outputs loaded with 50  $\Omega$  to  $V_{CC}$  2.0 V for proper operation.

- Vth is applied to the complementary input when operating in single-ended mode.
   VCMR<sub>MIN</sub> varies 1:1 with V<sub>EE</sub>, VCMR<sub>MAX</sub> varies 1:1 with V<sub>CC</sub>.
   Input and output voltage swing is a single-ended measurement operating in differential mode.
- 7. V<sub>BBAC</sub> used to rebias capacitor-coupled inputs only (see Figures 16 and 17).

Table 7. DC CHARACTERISTICS, LVTTL/LVCMOS INPUTS ( $V_{CC} = 2.375 \text{ V}$  to 3.465 V,  $V_{EE} = 0 \text{ V}$ ,  $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ )

Symbol	Characteristic	Min	Тур	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage (LVCMOS/LVTTL)	2.0		V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage (LVCMOS/LVTTL)	V <sub>EE</sub>		0.8	V
I <sub>IH</sub>	Input HIGH Current	-150		150	μΑ
I <sub>IL</sub>	Input LOW Current	-150		150	μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 8. AC CHARACTERISTICS  $V_{CC} = 2.375 \text{ V to } 3.465 \text{ V}; V_{EE} = 0 \text{ V (Note 8)}$ 

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>in</sub>	Maximum Input CLOCK Frequency			3.0			3.0			3.0	GHz
V <sub>OUTPP</sub>	$ \begin{array}{llll} & \text{Output Voltage Amplitude (Notes 10, 11)} \\ & \text{QA}(\div2,4,8),\text{QB}(\divn) & f_{in} \leq 3.0\;\text{GHz} \\ & \text{QA}(\div1),\text{QB}(\divn) & f_{in} \leq 2.5\;\text{GHz} \\ & \text{QA}(\div1),\text{QB}(\divn) & 2.5\;\text{GHz} < f_{in} \leq 3.0\;\text{GHz} \\ \end{array} $	450 450 300	650 650 650		450 450 250	650 630 650		450 450 200	650 610 650		mV
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay to CLK, Qn Output Differential @ 50 MHz MR, Qn	370 330	470 370	570 430	370 330	470 380	570 430	400 330	500 400	600 480	ps
t <sub>RR</sub>	Reset Recovery	0	-90		0	-90		0	-90		ps
t <sub>s</sub>	Setup Time @ 50 MHz EN, CLK SELA/B, CLK	0 0	-60 -300		0 0	-60 -300		0 0	-60 -300		ps
t <sub>h</sub>	Hold Time @ 50 MHz CLK, EN CLK, SELA/B	150 700	65 200		150 700	65 200		150 700	65 200		ps
t <sub>skew</sub>	Within–Device Skew @ 50 MHz (Note 9) Device–to–Device Skew (Note 9) Duty Cycle Skew (Note 9)		5 25 25	30 80 40		5 30 30	30 90 45		6 30 30	35 90 45	ps
t <sub>PW</sub>	Minimum Pulse Width MR	550			550			550			ps
t <sub>JITTER</sub>	RMS Random Clock Jitter (See Figure 20. F <sub>max</sub> /JITTER)			< 1			< 1			< 1	ps
V <sub>INPP</sub>	Input Voltage Swing (Differential Configuration) (Note 10)	100		V <sub>CC</sub> -V <sub>EE</sub>	100		V <sub>CC</sub> -V <sub>EE</sub>	100		V <sub>CC</sub> -V <sub>EE</sub>	mV
t <sub>r</sub>	Output Rise/Fall Times @ 50 MHz Qn, Qn Qn (20% – 80%)	30	60	120	30	65	120	30	70	120	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 8. Measured using a 750 mV, 50% duty cycle clock source. All loading with 50  $\Omega$  to V<sub>CC</sub> 2.0 V.
- Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.
- 10. Input and output voltage swing is a single–ended measurement operating in differential mode.
   11. Output Voltage Amplitude (V<sub>OHCLK</sub> V<sub>OLCLK</sub>) at input CLOCK frequency, f<sub>in</sub>. The output frequency, f<sub>out</sub>, is the input CLOCK frequency divided by n, f<sub>out</sub> = f<sub>in</sub> ÷ n. Input CLOCK frequency is ≤ 3.0 GHz.

# **Application Information**

The NB6L239 is a high–speed, low skew clock divider with two divider circuits, each having selectable clock divide ratios;  $\div 1/2/4/8$  and  $\div 2/4/8/16$ . Both divider circuits drive a pair of differential LVPECL outputs. The internal dividers are synchronous to each other. Therefore, the common output edges are precisely aligned.

The NB6L239 clock inputs can be driven by a variety of differential signal level technologies including LVDS, LVPECL, HSTL, or CML. The differential clock input buffer employs a pair of internal 50  $\Omega$  termination resistors in a 100  $\Omega$  center–tapped configuration and accessible via the VT pin. This feature provides transmission line termination on–chip, at the receiver end, eliminating external components. The V<sub>BBAC</sub> reference output can be used to rebias capacitor–coupled differential or

single–ended input CLOCK signals. For the capacitor–coupled CLK and/or  $\overline{CLK}$  inputs,  $V_{BBAC}$  should be connected to the  $V_T$  pin and bypassed to ground with a 0.01  $\mu F$  capacitor. Inputs CLK and  $\overline{CLK}$  must be signal driven or auto oscillation may result.

The common enable (EN) is synchronous so that the internal divider flip-flops will only be enabled/disabled when the internal clock is in the LOW state. This avoids any chance of generating a runt pulse on the internal clock when the device is enabled/disabled, as can happen with an asynchronous control. The internal enable flip-flop is clocked on the falling edge of the input clock. Therefore, all associated specification limits are referenced to the negative edge of the clock input.

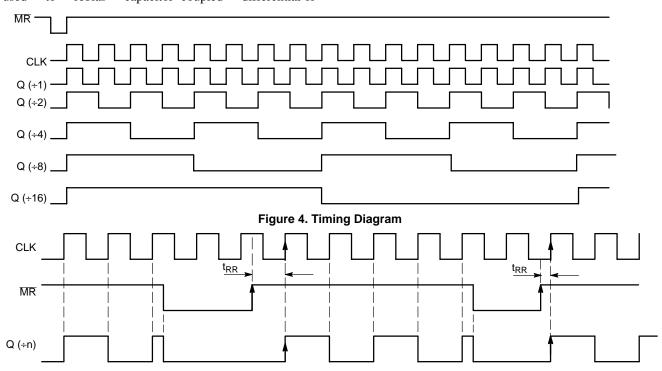


Figure 5. Master Reset Timing Diagram

NOTE: On the rising edge of MR, Q goes HIGH after the first rising edge of CLK.

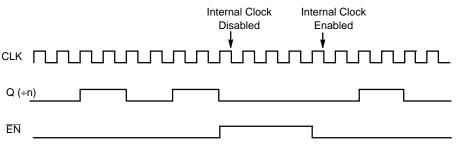
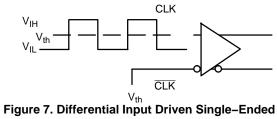


Figure 6. Output Enable Timing Diagrams

The  $\overline{EN}$  signal will "freeze" the internal divider flip–flops on the first falling edge of CLK after its assertion. The internal divider flip–flops will maintain their state during the freeze. When  $\overline{EN}$  is deasserted (LOW), and after the next falling edge of CLK, then the internal divider flip–flops will "unfreeze" and continue to their next state count with proper phase relationships.



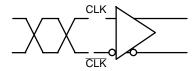


Figure 8. Differential Inputs Driven Differentially

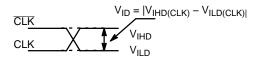


Figure 9. Differential Inputs Driven Differentially

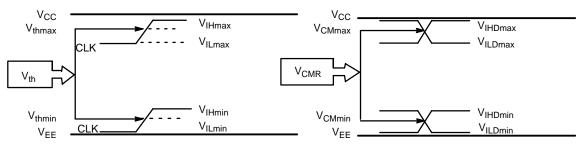


Figure 10. V<sub>th</sub> Diagram

Figure 11. V<sub>CMR</sub> Diagram

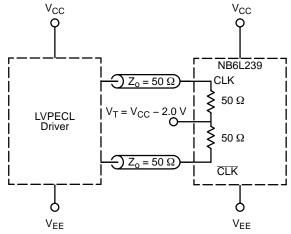


Figure 12. LVPECL Interface

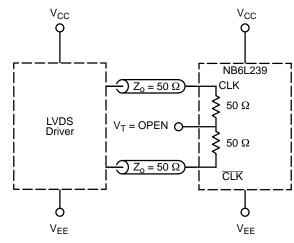


Figure 13. LVDS Interface

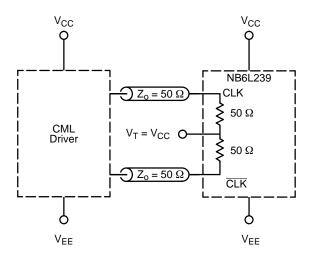


Figure 14. Standard 50  $\Omega$  Load CML Interface

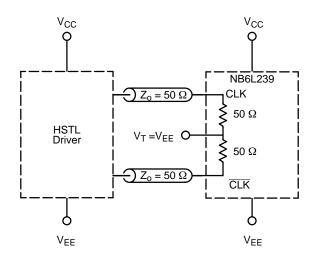


Figure 15. Standard 50  $\Omega$  Load HSTL Interface

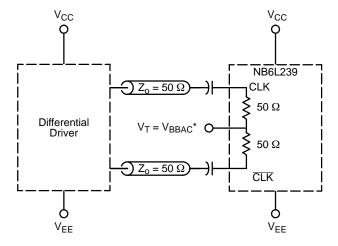
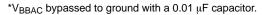


Figure 16. Capacitor–Coupled Differential Interface ( $V_T$  Connected to  $V_{BBAC}$ )



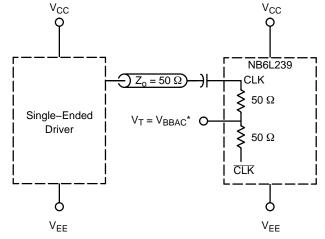


Figure 17. Capacitor–Coupled Single–Ended Interface ( $V_T$  Connected to  $V_{BBAC}$ )

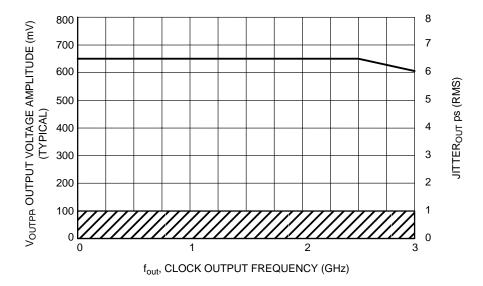


Figure 18. Output Voltage Amplitude ( $V_{OUTPP}$ )/RMS Jitter versus Clock Output Frequency at Ambient Temperature (Typical) ( $f_{out} = f_{in} \div n$ ).

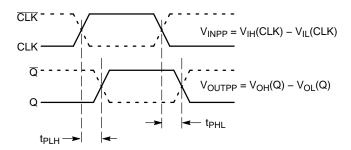


Figure 19. AC Reference Measurement

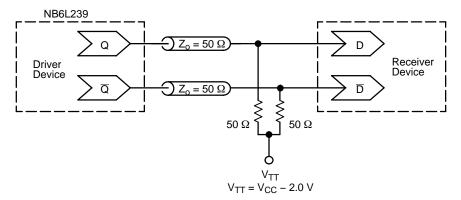


Figure 20. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>					
NB6L239MN	QFN-16	123 Units / Rail					
NB6L239MNR2 QFN-16		3000 / Tape & Reel					

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **Resource Reference of Application Notes**

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS I/O SPICE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1642/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

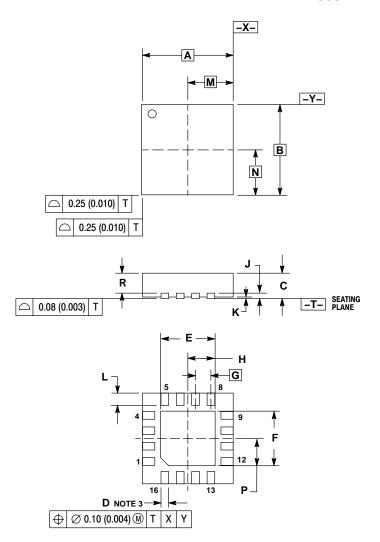
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

#### PACKAGE DIMENSIONS

QFN-16 CASE 485G-01 **ISSUE A** 



#### NOTES:

- DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING PER ANSI Y14-5M, 1982. CONTROLLING DIMENSION: MILLIMETERS. DIMENSION D APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	3.00 BSC		0.118 BSC	
В	3.00 BSC		0.118 BSC	
c	0.80	1.00	0.031	0.039
D	0.23	0.28	0.009	0.011
Е	1.75	1.85	0.069	0.073
F	1.75	1.85	0.069	0.073
G	0.50 BSC		0.020 BSC	
Н	0.875	0.925	0.034	0.036
7	0.20 REF		0.008 REF	
K	0.00	0.05	0.000	0.002
L	0.35	0.45	0.014	0.018
M	1.50 BSC		0.059 BSC	
N	1.50 BSC		0.059 BSC	
P	0.875	0.925	0.034	0.036
R	0.60	0.80	0.024	0.031

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